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TITLE: Method and arrangement for improving leak tolerance of  
an earpiece in a radio device

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INT-CL (IPC): H04M001/03, H04R001/22

EUR-CL (EPC): H04M001/03 ; H04R001/22

ABSTRACT:

CHG DATE=19990905 STATUS=O> The invention relates to an arrangement for improving leak tolerance in an earpiece (100) of a radio device. The invention can be applied preferably in mobile stations. One idea of the invention is that an acoustic volume (111) is arranged behind the earpiece by taking advantage of the RF shield casing (112, 116) of a radio frequency unit of the device. By means of the invention one can form behind the earpiece an acoustic volume which loads optimally the earpiece without therefore needing to enlarge the size of the device. In an embodiment of the invention one wall of the casing arranged behind the earpiece has been formed by means of an electronic circuit board (112), to which circuit board radio frequency components (117) of an electronic unit have been connected. Then between the casing and the external volume one can preferably form an acoustic path by means of through holes (113, 114) arranged in the circuit board. <IMAGE>

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Abstract Text - FPAR (1):

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Title of Patent Publication - TTL (1):

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